

Patent claims:

1. Lacquer formulations containing:

- 5 • from 5 to 99.5 wt.% of solids of a polymer component or of a mixture of two or more physically or chemically crosslinking polymer components,
- from 0 to 80 wt.% of a low molecular weight component acting as solvent or of a mixture of such low molecular weight components,
- 10 • from 0.5 to 50 wt.% of a silanised, structurally modified pyrogenic silica to the surface of which there are attached alkylsilyl groups ($\text{SiC}_n\text{H}_{2n+1}$, where n = from 2 to 18) and/or dimethylsilyl groups and/or monomethylsilyl groups,
- from 0 to 10 wt.% of commercially available additives.